## Amendments to the Claims:

Please cancel claims 7 and 13, replace claims 1-3, 5, 6, 9-12, 15-17, 19 and 34, all as shown below.

- 1. (Currently Amended) A method for shaping a surface of a workpiece, comprising:
  - placing the workpiece in a plasma processing chamber including an inductively-coupled plasma (ICP) torch having an outer tube to communicate a plasma gas to a distal end of the plasma torch and an inner tube nested within the outer tube to communicate a reactive precursor to the distal end, which does not require an electrode;

translating at least one of the workpiece and the plasma torch; and

using reactive atom plasma processing that:

communicating the plasma gas to the distal end;

- generating a plasma discharge by transferring transfers energy from a radio frequency (RF) power source to excite [[a]] the plasma gas, wherein a plasma sheath is formed between the distal end and the plasma discharge; and [[a]]
- introducing the reactive precursor to the plasma discharge through the inner tube to generate a reactive species in the plasma torch;
- sustains a sustaining the plasma discharge through collisions between the excited precursor and the plasma gas; and
- shapes shaping the surface of the workpiece by controlling a footprint of the plasma discharge from the plasma torch; and
- directs directing the plasma discharge to a target portion of the surface of the workpiece.
- 2. (Currently Amended) A method according to claim 1, wherein the step of using reactive plasma processing to shape shaping the surface of the workpiece comprises causing minimal or no damage to the workpiece underneath the surface.
- 3. (Currently Amended) A method according to claim 1, wherein the step of using reactive plasma processing to shape shaping the surface of the workpiece comprises removing material from the surface of the workpiece.

- 4. (Original) A method according to claim 1, further comprising: rotating the workpiece with respect to the plasma torch.
- 5. (Currently Amended) A method according to claim 1, wherein the step of plasma processing uses directing the plasma discharge includes directing that is a the reactive species to the target portion.
- 6. (Currently Amended) A method according to claim 1, further comprising: placing the <u>reactive</u> precursor in a central channel of the plasma torch.
- 7. (Canceled)
- 8. (Previously Presented) A method according to claim 1, further comprising: using an argon gas as the plasma gas.
- 9. (Currently Amended) A method according to claim 1, further comprising: controlling the mass flow of the <u>reactive</u> precursor into the plasma torch.
- 10. (Currently Amended) A method according to claim 1, further comprising: controlling the mass flow of the <u>reactive</u> precursor into the plasma torch from between about 0 ml/min to about 2,000 ml/min.
- 11. (Currently Amended) A method according to claim 1, further comprising: controlling the mass flow of the <u>reactive</u> precursor into the plasma torch from between about 0 ml/min to about 50,000 ml/min.
- 12. (Currently Amended) A method according to claim 1, further comprising: selecting a concentration of the <u>reactive</u> precursor to be introduced into <u>the plasma discharge</u> a <u>central channel of the plasma torch</u>.

- 13. (Canceled)
- 14. (Previously Presented) A method according to claim 1, further comprising: coupling the RF energy to the plasma discharge in an annular region of the plasma torch.
- 15. (Currently Amended) A method according to claim 1, wherein the plasma torch includes an intermediate tube arranged between the outer tube and the inner tube, the method further comprising: introducing an auxiliary gas into the intermediate tube through a second of three concentric tubes in the plasma torch.
- 16. (Currently Amended) A method according to claim [[1]] 15, further comprising: using an the auxiliary gas to keep the plasma discharge away from the inner tube a central channel of the plasma torch.
- 17. (Currently Amended) A method according to claim [[1]] 15, further comprising: using an the auxiliary gas to adjust the position of the plasma discharge relative to the distal end.
- 18. (Previously Presented) A method according to claim 1, further comprising: controlling the size of the plasma discharge by selecting the inner diameter of an outer tube of the plasma torch.
- 19. (Currently Amended) A method according to claim 1, further comprising: communicating introducing the plasma gas to the outer tube tangentially to form a vortex.
- 20. (Previously Presented) A method according to claim 1, further comprising: metering the precursor and/or the plasma gas flow in the plasma torch.
- (Previously Presented) A method according to claim 1, further comprising:
  maintaining the temperature of the plasma torch between 5,000 and 15,000 degrees C.

- 22. (Previously Presented) A method according to claim 1, further comprising: producing a volatile reaction product on the surface of the workpiece.
- (Original) A method according to claim 1, further comprising:
  maintaining the processing chamber at about atmospheric pressure.
- 24. (Previously Presented) A method according to claim 1, further comprising: cleaning the surface of the workpiece with the plasma torch.
- 25. (Previously Presented) A method according to claim 1, further comprising: polishing the surface of the workpiece with the plasma torch.
- 26. (Previously Presented) A method according to claim 1, further comprising: planarizing the surface of the workpiece with the plasma torch.
- 27. (Previously Presented) A method according to claim 1, further comprising: using a plasma torch with a multiple head to increase an etch rate of the plasma torch.
- 28. (Previously Presented) A method according to claim 1, further comprising: using the precursor to control an etch rate of the plasma torch.
- 29. (Previously Presented) A method according to claim 28, wherein: the precursor is any one of a solid, liquid, and gas.
- 30.-33. (Canceled)
- 34. (Currently Amended) A method for shaping an optic, comprising: placing an optic workpiece in a plasma processing chamber including an inductively-coupled plasma (ICP) torch having an outer tube to communicate a plasma gas to a distal end of the plasma torch and an inner tube nested within the outer tube to communicate a reactive

precursor to the distal end, which does not require an electrode;

translating at least one of the optic workpiece and the plasma torch; and

using reactive atom plasma processing that:

communicating the plasma gas to the distal end;

generating a plasma discharge by transferring transfers energy from a radio frequency (RF) power source to excite [[a]] the plasma gas, wherein a plasma sheath is formed between the distal end and the plasma discharge; and [[a]]

introducing the reactive precursor to the plasma discharge through the inner tube to generate a reactive species in the plasma torch;

sustains a sustaining the plasma discharge through collisions between the excited precursor and the plasma gas; and

shapes shaping the surface of the optic workpiece by controlling a footprint of the plasma discharge from the plasma torch; and

directs directing the discharge to a target portion of the surface of the optic workpiece.

Claims 35.-41. (Canceled)